



SLOVENSKI STANDARD
SIST EN 123400:2001/A2:1997
01-avgust-1997

**Sectional specification: Flexible printed boards without through connections -
Amendment to table IV of EN**

Sectional Specification: Flexible printed boards without through connections

Rahmenspezifikation: Flexible Leiterplatten ohne Durchverbindungen

Spécification intermédiaire: Cartes imprimées souples sans connexions transversales
(standards.iteh.ai)

Ta slovenski standard je istoveten z: EN 123400:1992/A2:1995

SIST EN 123400:2001/A2:1997
<https://standards.iteh.ai/catalog/standards/sist/1796ee4e-86f3-475b-9798-213b287e93c5/sist-en-123400-2001-a2-1997>

ICS:

31.180 Tiskana vezja (TIV) in tiskane Printed circuits and boards
plošče

SIST EN 123400:2001/A2:1997 en

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 123400/A2

August 1995

ICS 31.180

Descriptors: Flexible printed boards, without through connections, capability test, quality conformance inspection, test patterns

English version

**Sectional Specification:
Flexible printed boards without through connections**

Spécification intermédiaire:
Cartes imprimées souples sans
connexions transversales

Rahmenspezifikation:
Flexible Leiterplatten ohne
Durchverbindungen

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This amendment A2 modifies the European Standard EN 123400:1992; it was approved by CENELEC on 1995-07-04. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this amendment the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This amendment exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

This amendment was prepared by CLC/TC CECC/WG 23.

The text of the draft was submitted to the Unique Acceptance Procedure and was approved by CENELEC as amendment A2 to EN 123400:1992 on 1995-07-04.

The following dates were fixed:

- latest date by which the amendment has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 1996-07-01
 - latest date by which the national standards conflicting with the amendment have to be withdrawn (dow) 1996-07-01
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Amendment A2 to EN 123400:1992

Introduce the data on pages 3, 4 and 5 of this amendment into table IV of EN 123400.

NOTE: The asterisk denotes a changed or new characteristic.

Table IV

Inspection Group	Characteristic	Test No	Level A		Level C	
			IL	AQL	IL	AQL
Group A						
Sub-Group A1						
	Visual Inspection					
	Conformity	1	S2	2.5%	100%	
	Identification	1	S2	2.5%	100%	
	Appearance	1a	S2	2.5%	100%	
	Workmanship	1a	S2	2.5%	100%	
	Board Edges	1a	S2	2.5%	100%	
	Bonding: Conductor to Substrate	1a	S2	2.5%	100%	
	Bonding: Coverlayer to Substrate and Pattern	1a	S2	2.5%	100%	
	* Bonding: Flexible Substrate to rigidising component	1a	S2	2.5%	100%	
	* Conductor Defects	1a	S2	2.5%	100%	
	* Misalignment of Access Hole and Land	1a	S2	2.5%	100%	
	Particles between conductors	1b, 1c	S2	2.5%	100%	
Sub-Group A2						
	Dimensional Examination					
	Board Dimensions	2	S1	4.0%	S4	2.5%
	Holes	2	S1	4.0%	S4	2.5%
	Slots, Notches	2	S1	4.0%	S4	2.5%
	Conductor Width	2	S1	4.0%	S4	2.5%
	Conductor Spacing	2	S1	4.0%	S4	2.5%
	Misalignment of Hole and Land	2	S1	4.0%	S4	2.5%
	Positional Tolerance of Hole Centres	2	S1	4.0%	S4	2.5%
	* Misalignment of Access Hole and Land	2a	S1	4.0%	S4	2.5%
Sub-Group A3						
	Spare group for additional A tests					

Inspection Group	Characteristic	Test No	Level A		Level C	
			IL	AQL	IL	AQL
<u>Group B</u>						
<u>Sub-Group B1</u>	<u>Dimensional Interchangeability</u> Not Applicable					
<u>Sub-Group B2</u>	<u>Solderability</u> Unconditioned * After accelerated ageing	14a 20a	S2 -	2.5% -	S3 S3	2.5% 2.5%
<u>Sub-Group B3</u>	* <u>Thermal Shock Tests</u> Interlaminar Bond	#	-	-	S2	2.5%
<u>Sub-Group B4</u>	<u>Mechanical Tests</u> Peel Strength: Conductor to Substrate Pull-off strength, lands with plain holes * Peel Strength: Coverlayer to Conductor * Peel Strength: Flexible Substrate to Rigidising Component	10a 11a 11b 10c	- - - -	- - - -	S2 S2 S2 S2	2.5% 2.5% 2.5% 2.5%
<u>Sub Group B5</u>	<u>Surface Finish Tests</u> Adhesion of Plating * Thickness of edge * Edge Plating Porosity	#13a 13f #13d ,13e	S1 - - -	2.5% - - -	S2 S2 S2 S2	2.5% 2.5% 2.5% 2.5%

Inspection Group	Characteristic	Test No	Level A		Level C	
			No of Specimens	Accept: Reject	No of Specimens	Accept: Reject
Group C						
Sub-Group C1	Test Interval: 3 Months					
	* Process Contamination	#	-	-	20	1:2
	* Solvent Resistance Coverlayer / Resist	#	-	-	6	1:2
	* Resistance to Solder Coverlayer / resist	#	-	-	6	1:2
	* Flexural Fatigue	#21a	-	-	6	1:2

NOTES:

1. The symbol # denotes that the testing detail shall be included in the relevant Capability Detail Specification.
2. This listing may be subject to continuing review, as required by the publication of new Capability Detail Specifications.

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